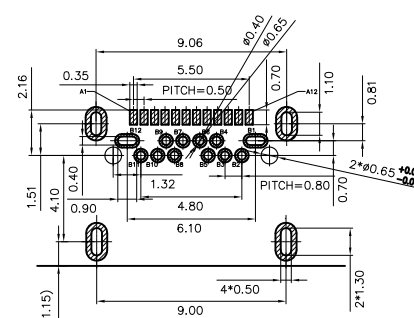
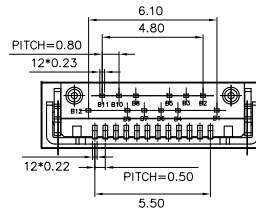
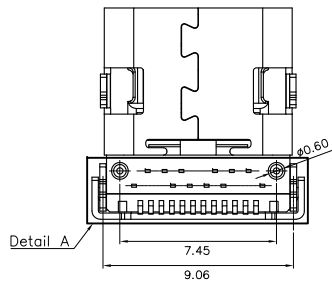
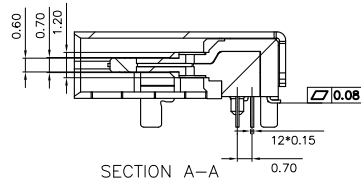
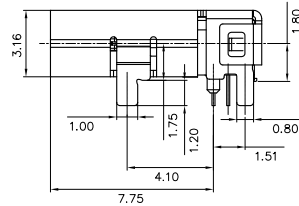
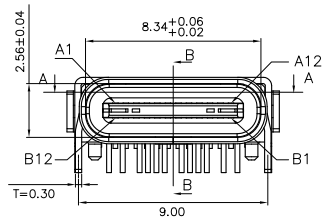


SPECIFICATION
 1.MATERIAL: See drawing
 2.STANDARD DATA
 2.1Rating current:5.0A for vBUS
 0.25A MIN FOR OTHER.
 VOLTAGE: 5VAC MAX
 3.ELECTRICAL
 3.1.insulator resistance: 100M ohms Min.
 3.2.Withstanding voltage: 100 VAC / minute
 3.3.Contact resistance: initial 40mohms Max.
 after 50mohms Max.
 4.MECHANICAL
 4.1Mating force: 5~20N
 4.2Unmating force : Initial 8~20N
 After 10000cycles 6~20N
 4.3Durability: 10000 cycles Min.

PART NO. 894D 1 3 -0824 24 009
 SERIES D=I/O Connector TYPE 1=0.5mm pitch CONTACT TYPE 3=SMT type
 MODEL NO. TYPE NO. 009=Type 9 CONTACT NUMBER 24=24position




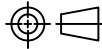
RECOMMEND P.C.B LAYOUT (COMPONENT SIDE)
 TOLERANCE FOR PCB LAYOUT IS ±0.05
 KEEP OUT AREA

USB TYPE-C FULL-FEATURED RECEPTACLE
 INTERFACE PIN ASSIGNMENTS

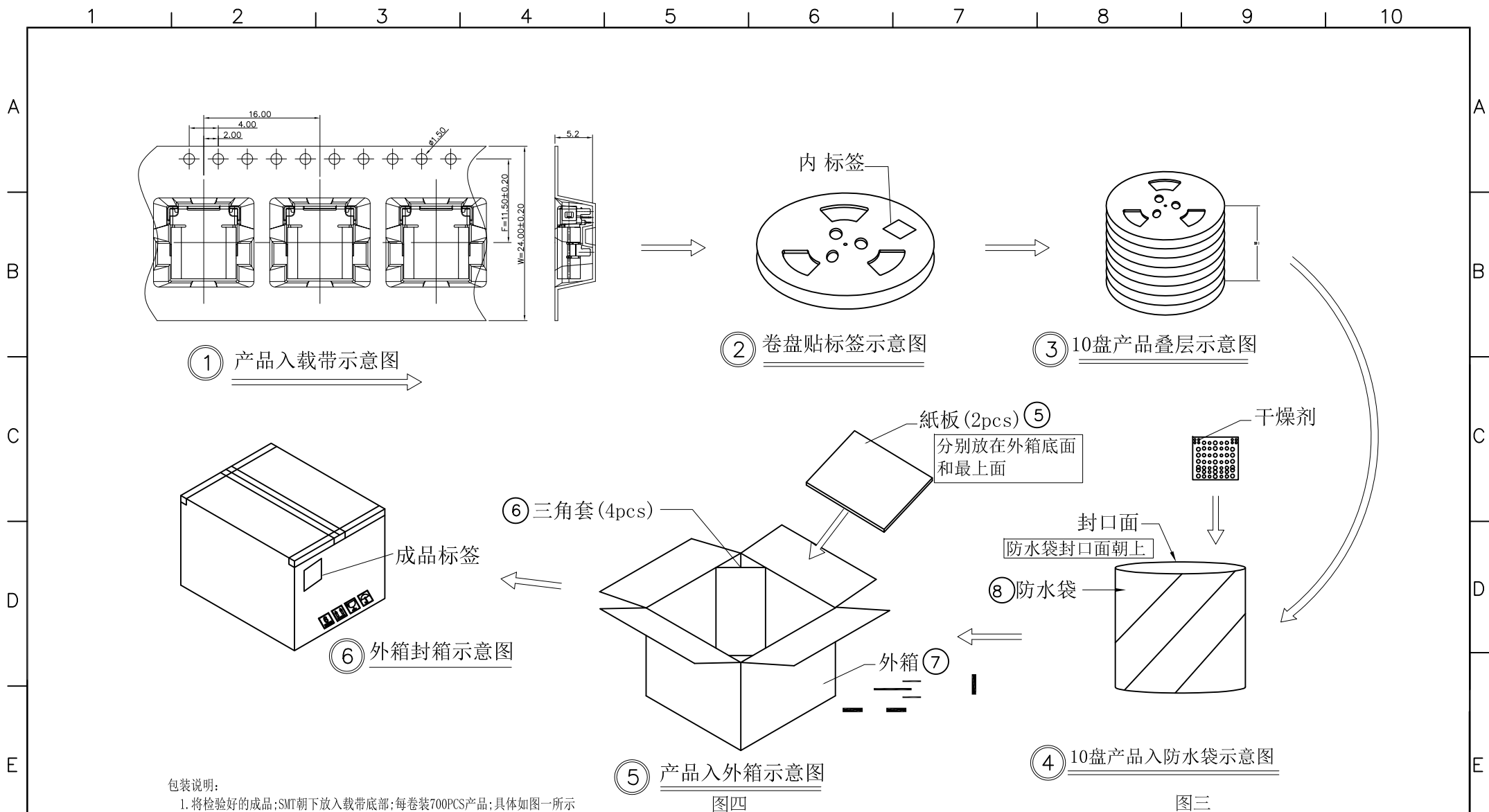
PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTxp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of first SuperSpeed RX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair
A4	Vbus	Bus Power	B9	Vbus	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use (SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use (SBU)	B5	CC2	Configuration Channel
A9	Vbus	Bus Power	B4	Vbus	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair
A12	GND	Ground return	B1	GND	Ground return

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ITEM 項目	PARTS NAME 零件名稱	Q'TY 數量	MATERIAL 材質	FINISH/REMARK 處理/備註
1	Insemold housing	1	SYNTHETIC RESIN	Black
2	CONTACT	1	COPPER ALLOY	PLATED GOLD ON CONTACT AREA, G/F GOLD ON SOLDER AREA, 50u" NICKEL PLATING OVER ALL.
3	SHELL	1	STAINLESS	Ni: 50u" Min
4	Shield	1	STAINLESS	

.X ± 0.30	APPROVED: Chris	 http://www.rego.com.tw	
.XX ± 0.20	CHECKED: Andy		
.XXX ± 0.15	DRAWN: Vic		
X* ± 3'	UNITS: mm	SCALE: NONE	TITLE: USB 3.1 Type C DIP+SMD
			PART NO: 894D13-082424009
			SHEET: 1 OF 2

A	02.7.2018
REV	DATE




图四

图三

包装说明:

1. 将检验好的成品;SMT朝下放入载带底部;每卷装700PCS产品;具体如图一所示
2. 将包装好的产品;每盘必需贴上内标签;具体如图二所示
3. 将贴好内标签的产品每10盘叠一层装入防水袋中并加一包干燥剂;装好后将防水袋封好;具体如图三图四所示
4. 先将1pcs平卡放入纸箱底部;然后将装好产品的防水袋装入纸箱中;防水袋热熔封口,封口面需朝上;并将4PCS三角套分别装入4个角;如图五所示
5. 装好后将1pcs平卡放入纸箱最上面并封好纸箱及贴好相关标签;具体如图六所示;(产品包装的标签,如客户有要求,请按客户要求包装出货)
6. 载带前面留30PCS空格,后面留20PCS空格
7. COVER与CARRY剥离力:50-125g,速度:300mm/分钟左右,剥离角度:165° -180°

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.X ± 0.30	APPROVED: Chris	 http://www.rego.com.tw	
.XX ± 0.20	CHECKED: Andy		
.XXX ± 0.15	DRAWN: Vic		
X* ± 3'	UNITS: mm	SCALE: NONE	TITLE: USB 3.1 Type C DIP+SMD
			PART NO: 894D13-082424009
			SHEET: 2 OF 2

A	02.7.2018
REV	DATE